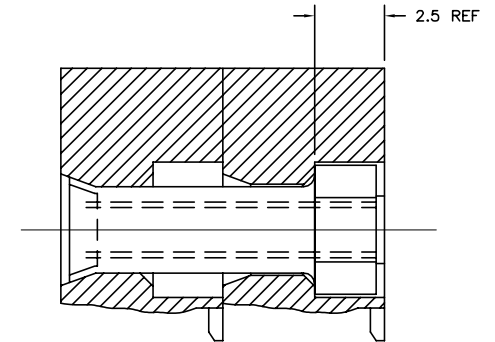
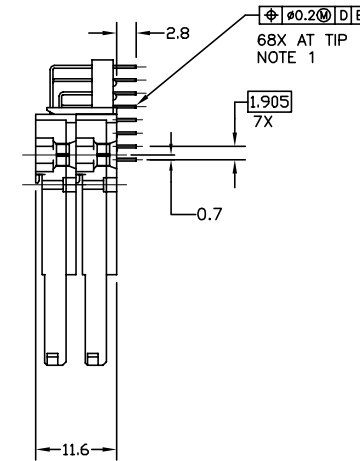
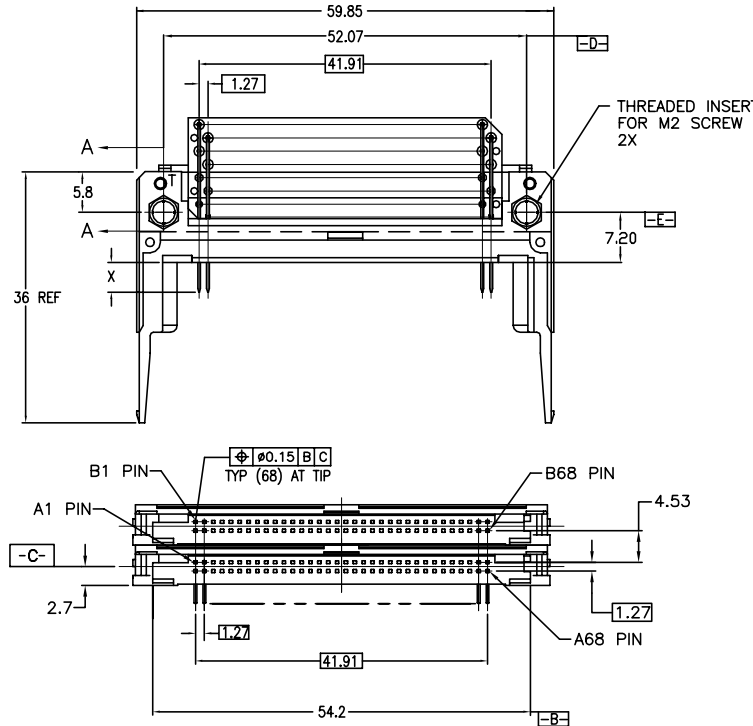


PRODUCT NO	DIM X			MOUNTING STYLE	COLOR
	4.25±0.1	3.5±0.1	5.0±0.1		
95705-000	OTHERS	36,67	1,17,34 35,51,68	TOP W\O LOCATOR	BLACK
95705-000LF	OTHERS	36,67	1,17,34 35,51,68	TOP W\O LOCATOR	BLACK



SECTION A-A  
SCALE 8/1

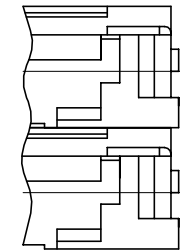
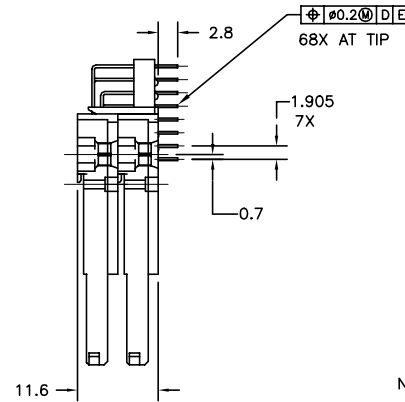
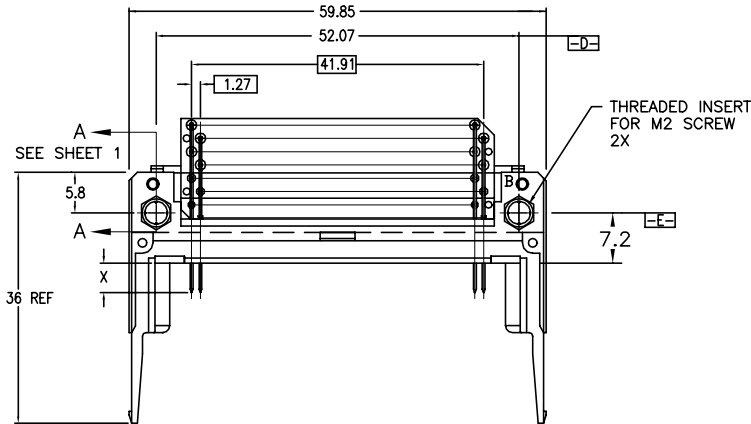
NOTES:

- TRUE POSITION IS A FREE GRID TO THE PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL:  
PLASTIC: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
PIN: COPPER ALLOY
- FINISH (PIN):  
UNDER PLATING: 0.5 µM MIN. Ni  
CONTACT AREA: 0.076 µM MIN. GOLD  
SOLDER AREA: 2.5 µM MIN. Sn-Pb  
: 2.5 µM MIN. PURE Sn ( FOR -\*\*\*LF)
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263

mat'l. code		surface		tolerance		projection		product family	
		ISO1302		ISO406 ISO1101		MM		PCMCIA	
ltr	ecr	nodr	date	tolerances unless otherwise specified		MM		title	
A	V50549	SSD	07/17/95	angle	0.X±0.3	scale 1:1		3.3VOLT DOUBLE DECK HEADER	
B	T50281	GAH	10/20/95	0°±2'	0.XX±0.13			dwg no	
C	V12164	TFG	08/17/01		0.XXX±0.05			sheet 1 of 4	
D	N05-0174	WB	06/16/05	dr	S.DUESERHOEF	07/17/95		size	
E	ELX-N-007956	ZK	11/01/11	engr	D.BRANN	07/17/95		A4	
F	ELX-N-01144	ZK	04/24/12	chr	D.BRANN	07/17/95		95705	
				appd	D.BRANN	07/17/95		type Product Customer Drawing	
sheet	revision	F	F	F	F				
index	sheet	1	2	3	4				



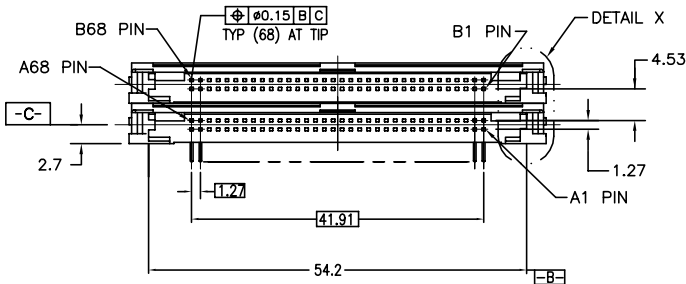
	PRODUCT NO			DIM X	MOUNTING STYLE	COLOR
	4.25±0.1	3.5±0.1	5.0±0.1			
95705-500	OTHERS	36,67	1,17,34 35,51,68		BOTTOM W\O LOCATOR	NATURAL (WHITE)
95705-500LF	OTHERS	36,67	35,51,68		BOTTOM W\O LOCATOR	NATURAL (WHITE)



DETAIL X  
SCALE: 3/1

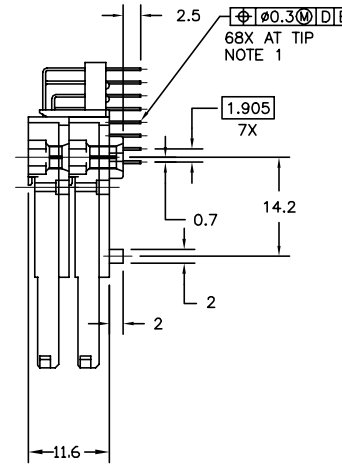
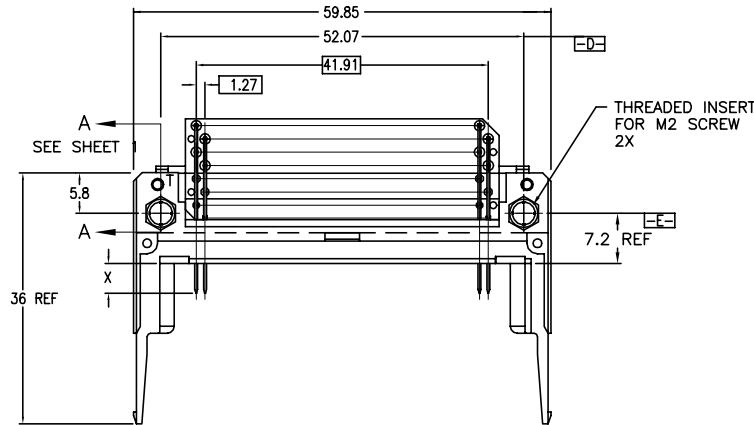
NOTES:

- TRUE POSITION IS A FREE GRID TO THE PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL:  
PLASTIC: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
PIN: COPPER ALLOY
- FINISH (PIN):  
UNDER PLATING: 0.5  $\mu$ M MIN. Ni  
CONTACT AREA: 0.076  $\mu$ M MIN. GOLD  
SOLDER AREA: 2.5  $\mu$ M MIN. Sn-Pb  
: 2.5  $\mu$ M MIN. PURE Sn ( FOR -\*\*\*LF)
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263



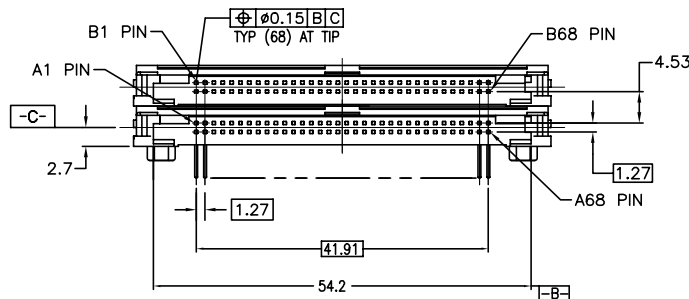
mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection MM	product family PCMCIA
ltr ecn nodr date	tolerances unless otherwise specified	angle 0°±2'	scale 1:1	title 3.3VOLT DOUBLE DECK HEADER
F		0.X±0.3 0.XX±0.13 0.XXX±0.05		dwg no 95705
	dr S.DUESERHOEF 07/17/95			sheet 2 of 4 size A4
	enr D.BRANN 07/17/95			type Product Customer Drawing
	chr D.BRANN 07/17/95			
	appd D.BRANN 07/17/95			
sheet index	revision sheet			

PRODUCT NO.	DIM X			MOUNTING STYLE	COLOR
	4.25±0.1	3.5±0.1	5.0±0.1		
95705-040	OTHERS	36,67	1,17,34 35,51,68	TOP W\O LOCATOR	BLACK
95705-040LF	OTHERS	36,67	1,17,34 35,51,68	TOP W\O LOCATOR	BLACK



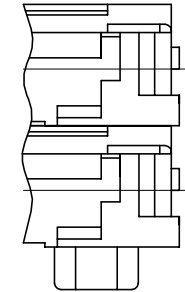
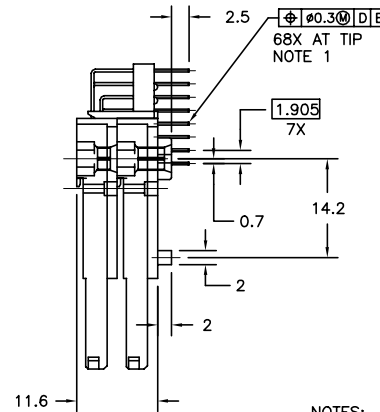
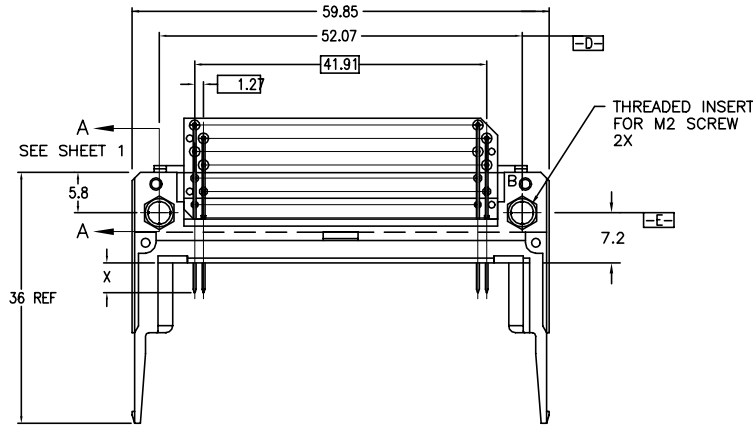
NOTES:

- TRUE POSITION IS A FREE GRID TO THE PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL:  
PLASTIC: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
PIN: COPPER ALLOY
- FINISH (PIN):  
UNDER PLATING: 0.5 µM MIN. Ni  
CONTACT AREA: 0.076 µm MIN. GOLD  
SOLDER AREA: 2.5 µM MIN. Sn-Pb  
: 2.5 µM MIN. PURE Sn ( FOR -\*\*\*LF)
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263



mat'l. code	surface ISO1302 ✓	tolerance ISO406 ISO1101	projection MM	product family PCMCIA
l trechn nodr	date	tolerances unless otherwise specified	scale 1:1	title 3.3VOLT DOUBLE DECK HEADER
F		angle 0°±2'		dwg no 95705
		dr S.DUESERHOEF 07/17/95		sheet 3 of 4
		enr D.BRANN 07/17/95		size A4
		chr D.BRANN 07/17/95		type Product Customer Drawing
		appd D.BRANN 07/17/95		
sheet index	revision sheet			

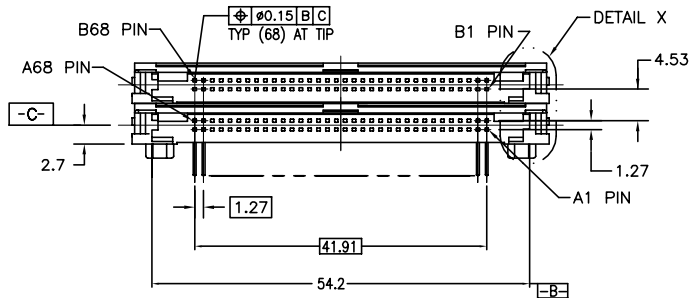
PRODUCT NO	DIM X			MOUNTING STYLE	COLOR
	4.25±0.1	3.5±0.1	5.0±0.1		
95705-540	OTHERS	36,67	1,17,34 35,51,68	BOTTOM W\O LOCATOR	NATURAL (WHITE)
95705-540LF	OTHERS	36,67	1,17,34 35,51,68	BOTTOM W\O LOCATOR	NATURAL (WHITE)



DETAIL X  
SCALE: 3/1

NOTES:

- TRUE POSITION IS A FREE GRID TO THE PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL:  
PLASTIC: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
PIN: COPPER ALLOY
- FINISH (PIN):  
UNDER PLATING: 0.5 μM MIN. Ni  
CONTACT AREA: 0.076 μM MIN. GOLD  
SOLDER AREA: 2.5 μM MIN. Sn-Pb  
: 2.5 μM MIN. PURE Sn ( FOR -\*\*LF)
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263



mat'l. code	surface	tolerance	projection	product family
ISD1302	✓	ISD406 ISD1101	MM	PCMCIA
l trechn nodr date	tolerances unless otherwise specified		scale 1:1	title
F	angle	0.X±0.3	MM	3.3VOLT DOUBLE DECK HEADER
	0°±2'	0.XX±0.13		
		0.XXX±0.05		
dr	S.DUESERHOEF	07/17/95	FCI	dwg no
enr	D.BRANN	07/17/95		sheet 4 of 4
chr	D.BRANN	07/17/95		size
appd	D.BRANN	07/17/95		A4
sheet index	revision sheet			type Product Customer Drawing